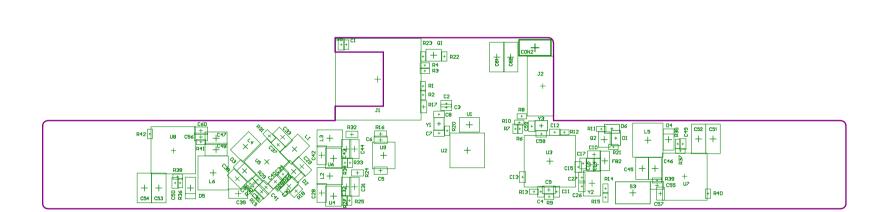
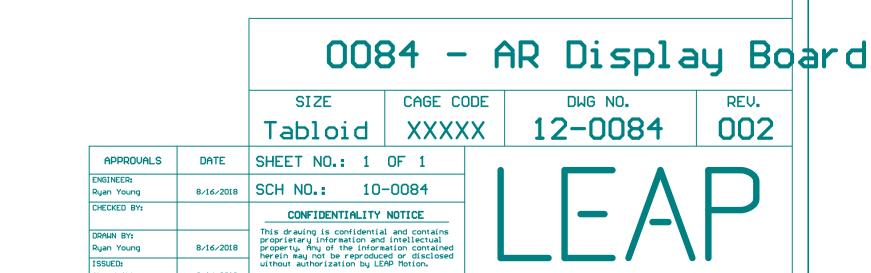
ECO Change Description	Date	Rev.	
	8/16/2018	2.1	
	3/18/2018	2.0	
	7/19/2017	1.0	



ASSEMBLY NOTES

- This drawing is CAD generated. No changes shall be made without LEAP Motion's consent.
 Use only no-clean RoHS compliant solder.
 Assemble and solder per J-STD-001, Class 2.
 Prior to shipment, each assembly must be packaged seperately in a static shielding bag in a manner that protects from physical damage.
 Inspect to IPC-A-610, Class 2.
 DFM report is required for all first article builds.
 Board revision shall be written/labeled in the space provided on the board.



Layer / Function

Mechanical 1 / Board Outline:

Top Solder:
Top Paste:
Top Overlay:
L1(TOP):
L2(GND):
L3(GND):

Bottom Overlay: Bottom Paste: Bottom Solder:

L4(BOT):

EXT.

.GTS .GTP .GTO .GTL .GP1

.GBL .GBO .GBP .GBS .GM1

File Name

12-0084 12-0084 12-0084 12-0084 12-0084 12-0084

12-0084 12-0084 12-0084 12-0084 12-0084

ECO Change Description	Date	Rev.
	8/16/2018	2.1
	3/18/2018	2.0
	7/19/2017	1.0

Layer / Function	File Name	EXT.
Top Solder: Top Paste: Top Overlay: L1(TOP): L2(GND): L3(GND):	12-0084 12-0084 12-0084 12-0084 12-0084	.GTS .GTP .GTO .GTL .GP1 .GP2
L4(BOT): Bottom Overlay: Bottom Paste: Bottom Solder: Mechanical 1 / Board Outline:	12-0084 12-0084 12-0084 12-0084 12-0084	.GBL .GBO .GBP .GBS



- This drawing is CAD generated. No changes shall be made without LEAP Motion's consent.
 Use only no-clean RoHS compliant solder.
 Assemble and solder per J-STD-001, Class 2.
 Prior to shipment, each assembly must be packaged seperately in a static shielding bag in a manner that protects from physical damage.
 Inspect to IPC-A-610, Class 2.
 DFM report is required for all first article builds.
 Board revision shall be written/labeled in the space provided on the board.

Ryan Young

